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FC1-2	Reliability of Silicone and Epoxy Resin Encapsulated Power Modules in HV-H3TRB Tests with Thin-Resin Coated Dice	Felix Steiner ¹ , Helge Wurst ¹ , Benjamin Leyrer ¹ , Dai Ishikawa ² , Hideo Nakako ² , Thomas Blank ¹ , ¹ Karlsruhe Institute of Technology / Germany, ² Showa Denko Materials / Japan	147
FC1-3	Effect of Gate Pad Layout on Thermal Impedance of SiC-MOSFET	F. Kato, S. Sato, H. Hozoji, M. Ikegawa, A. Sakai, K. Watanabe, S. Harada, H. Sato, National Institute of Advanced Industrial Science and Technology / Japan	149

FC1-4	Cu-Sintering on Organic Packages for Power Modules	Hans-Jürgen Albrecht ¹ , Dirk Busse ¹ , Alexander Dahlbüding ¹ , Aaron Hutzler ² , Olaf Rämmer ³ , Ichiro Ota ⁴ , Hideo Nakako ⁵ , Florian Pape ⁴ , Dewi Nilasari ⁵ , ¹ budatec, ² BondPulse, ³ Fraunhofer Gesellschaft / Germany, ⁴ Showa Denko Materials / Japan, ⁵ Isola Group / Germany	151
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FC2-4	Estimation of Switching Transients and Power Losses of SiC-based Power MOSFET Inverter Using Electromagnetic-circuit Co-simulation During Six-step Commutation	Yan-Cheng Liu ^{1,2} , Hsien-Chie Cheng ¹ , Hsin-Han Lin ² , Shian-Chiau Chiou ² , Sheng-Tai Wu ² , Tao-Chih Chang ² , ¹ Feng Chia University, ² Industrial Technology Research Institute / Taiwan	159

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FC3-2	FPGA-driven High Density Photonic Reservoir Computing	Hidetoshi Numata ¹ , Jean Benoit Heroux ² , Toshiyuki Yamane ¹ , Daiju Nakano ¹ , ¹ IBM Research / Japan, ² IBM Systems / Canada	161
FC3-3 <Session Invited>	Hollow-Core Fiber Connector	Ryo Nagase ¹ , Hideki Kamitsuna ² , Toshiki Maejima ¹ , Ryuta Matsuda ¹ , ¹ Chiba Institute of Technology, ² YOKOWO / Japan	-

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FD1-1	Electrochemical Analysis of Initial Oxide Layers on Copper Surface	Chi-Hsuan Lin ¹ , Wei-Ting Chen ¹ , Yu-Cheng Ke ¹ , Jenn-Ming Song ^{1,2} , Kiyokazu Yasuda ² , ¹ National Chung Hsing University / Taiwan, ² Osaka University / Japan	163
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FD1-3	Platinum Interconnections for Harsh Environment Applications Using Atmospheric Pressure Sputtering	J. Bickel ^{1,3} , M. Schneider-Ramelow ^{2,3} , K.-D. Lang ^{2,3} , R. Gesche ⁴ , H.-D. Ngo ^{1,2} , ¹ University of Applied Sciences, ² Fraunhofer IZM, ³ Technische Universität Berlin, ⁴ Beaplas / Germany	167
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FD2-2	Comparison of the Mechanical Properties of Conventional Pb-Free Solders and Eutectic Sn-Bi Solder	Qichao Hao ¹ , Xin Fu Tan ¹ , Stuart D. McDonald ¹ , Keith Sweatman ^{1,2} , Takatoshi Nishimura ² , Tetsuro Nishimura ² , Kazuhiro Nogita ¹ , ¹ The University of Queensland / Australia, ² Nihon Superior / Japan	173
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FD2-4	Investigation of the Effects of Surface Finish and Reflow Conditions on the Microstructure and Mechanical Properties of Sn-Based Solders	Flora Somidin ^{1, 2} , Tetsuya Akaiwa ³ , Stuart D. McDonald ² , Tetsuro Nishimura ² , Xiaozhou Ye ² , Anthony Smith ² , Jiye Zhou ² , Kazuhiro Nogita ² , ¹ The University of Queensland / Australia, ² Universiti Malaysia Perlis / Malaysia, ³ Nihon Superior / Japan	177

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